

U.S. Patent Application Serial No. 09/337,278
Amendment filed August 20, 2004
Reply to OA dated April 20, 2004

IN THE CLAIMS

Please cancel claims 3, 7, 9, and 11-19 without prejudice or disclaimer, amend claims 1, 5 and 10, and add new claims 20-22, as follows:

Claim 1 (Currently amended): A method of cleaning an ~~alumina-titanium carbide~~ electronic component comprising bringing a sponge member into contact with an ~~the~~ ~~alumina titanium carbide~~ object to be cleaned while supplying, to said ~~alumina titanium carbide~~ object to be cleaned, a solution consisting essentially of water containing and carbon dioxide gas having a resistivity value of less than 5 MΩ,

wherein said sponge member is separated from said object to be cleaned during cleaning, and said solution is supplied also to the separated sponge member, wherein contaminants are removed from the sponge member.

Claims 2-4 (Canceled).

Claim 5 (Original): A method of cleaning an ~~alumina-titanium carbide~~ electronic component according to claim 1, wherein said ~~alumina-titanium carbide~~ object to be cleaned is a ceramic wafer.

Claim 6-9 (Canceled).

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Claim 10 (Currently amended): A method of cleaning an electronic component according to ~~any one of claims~~ claim 1, ~~3, or 5, 7 or 9,~~ wherein said ~~alumina titanium carbide~~ object to be cleaned is soaked in water having a resistivity value of 10M Ω or less before cleaning.

Claims 11-19 (Canceled).

Claim 20 (New): The method according to claim 1, wherein said object to be cleaned is made of aluminum titanium carbide.

Claim 21 (New): The method according to claim 1, wherein said solution has a resistivity value of 0.5 M Ω or less.

Claim 22 (New): The method according to claim 1, wherein said solution has a resistivity value of 0.3 M Ω or less.